

LM317L, NCV317L

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Input-Output Voltage Differential	$V_I - V_O$	40	Vdc
Power Dissipation Case 29 (TO-92) $T_A = 25^\circ\text{C}$ Thermal Resistance, Junction-to-Ambient Thermal Resistance, Junction-to-Case	P_D $R_{\theta JA}$ $R_{\theta JC}$	Internally Limited 160 83	W $^\circ\text{C/W}$ $^\circ\text{C/W}$
Case 751 (SOIC-8) (Note 1) $T_A = 25^\circ\text{C}$ Thermal Resistance, Junction-to-Ambient Thermal Resistance, Junction-to-Case	P_D $R_{\theta JA}$ $R_{\theta JC}$	Internally Limited 180 45	W $^\circ\text{C/W}$ $^\circ\text{C/W}$
Maximum Junction Temperature	T_{JMAX}	+150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-65 to +150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- SOIC-8 Junction-to-Ambient Thermal Resistance is for minimum recommended pad size. Refer to Figure 24 for Thermal Resistance variation versus pad size.
- This device series contains ESD protection and exceeds the following tests:
Human Body Model, 2000 V per MIL STD 883, Method 3015.
Machine Model Method, 200 V.

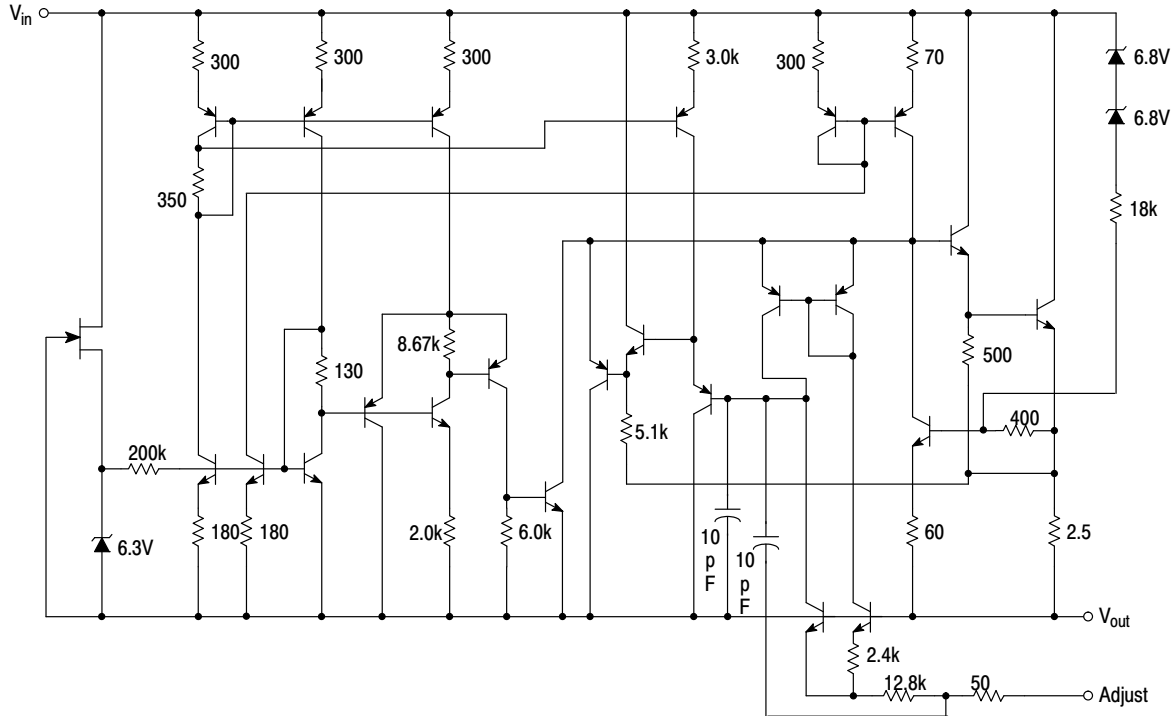


Figure 1. Representative Schematic Diagram

LM317L, NCV317L

ELECTRICAL CHARACTERISTICS

($V_I - V_O = 5.0\text{ V}$; $I_O = 40\text{ mA}$; $T_J = T_{\text{low}}$ to T_{high} (Note 3); I_{max} and P_{max} (Note 4); unless otherwise noted.)

Characteristics	Figure	Symbol	LM317L, LB, NCV317LB			Unit
			Min	Typ	Max	
Line Regulation (Note 5) $T_A = 25^\circ\text{C}$, $3.0\text{ V} \leq V_I - V_O \leq 40\text{ V}$	1	Reg_{line}	–	0.01	0.04	%/V
Load Regulation (Note 5), $T_A = 25^\circ\text{C}$ $10\text{ mA} \leq I_O \leq I_{\text{max}}$ – LM317L $V_O \leq 5.0\text{ V}$ $V_O \geq 5.0\text{ V}$	2	Reg_{load}	– –	5.0 0.1	25 0.5	mV % V_O
Adjustment Pin Current	3	I_{Adj}	–	50	100	μA
Adjustment Pin Current Change $2.5\text{ V} \leq V_I - V_O \leq 40\text{ V}$, $P_D \leq P_{\text{max}}$ $10\text{ mA} \leq I_O \leq I_{\text{max}}$ – LM317L	1, 2	ΔI_{Adj}	–	0.2	5.0	μA
Reference Voltage $3.0\text{ V} \leq V_I - V_O \leq 40\text{ V}$, $P_D \leq P_{\text{max}}$ $10\text{ mA} \leq I_O \leq I_{\text{max}}$ – LM317L	3	V_{ref}	1.20	1.25	1.30	V
Line Regulation (Note 5), $3.0\text{ V} \leq V_I - V_O \leq 40\text{ V}$	1	Reg_{line}	–	0.02	0.07	%/V
Load Regulation (Note 5) $10\text{ mA} \leq I_O \leq I_{\text{max}}$ – LM317L $V_O \leq 5.0\text{ V}$ $V_O \geq 5.0\text{ V}$	2	Reg_{load}	– –	20 0.3	70 1.5	mV % V_O
Temperature Stability ($T_{\text{low}} \leq T_J \leq T_{\text{high}}$)	3	T_S	–	0.7	–	% V_O
Minimum Load Current to Maintain Regulation ($V_I - V_O = 40\text{ V}$)	3	I_{Lmin}	–	3.5	10	mA
Maximum Output Current $V_I - V_O \leq 6.25\text{ V}$, $P_D \leq P_{\text{max}}$, Z Package $V_I - V_O \leq 40\text{ V}$, $P_D \leq P_{\text{max}}$, $T_A = 25^\circ\text{C}$, Z Package	3	I_{max}	100 –	200 20	– –	mA
RMS Noise, % of V_O $T_A = 25^\circ\text{C}$, $10\text{ Hz} \leq f \leq 10\text{ kHz}$	–	N	–	0.003	–	% V_O
Ripple Rejection (Note 6) $V_O = 1.2\text{ V}$, $f = 120\text{ Hz}$ $C_{\text{Adj}} = 10\text{ }\mu\text{F}$, $V_O = 10.0\text{ V}$	4	RR	60 –	80 80	– –	dB
Thermal Shutdown (Note 7)	–	–	–	180	–	$^\circ\text{C}$
Long Term Stability, $T_J = T_{\text{high}}$ (Note 8) $T_A = 25^\circ\text{C}$ for Endpoint Measurements	3	S	–	0.3	1.0	%/1.0 k Hrs.

3. T_{low} to $T_{\text{high}} = 0^\circ$ to $+125^\circ\text{C}$ for LM317L -40° to $+125^\circ\text{C}$ for LM317LB, NCV317LB

4. $I_{\text{max}} = 100\text{ mA}$ $P_{\text{max}} = 625\text{ mW}$

5. Load and line regulation are specified at constant junction temperature. Changes in V_O due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

6. C_{Adj} , when used, is connected between the adjustment pin and ground.

7. Thermal characteristics are not subject to production test.

8. Since Long-Term Stability cannot be measured on each device before shipment, this specification is an engineering estimate of average stability from lot to lot.

LM317L, NCV317L

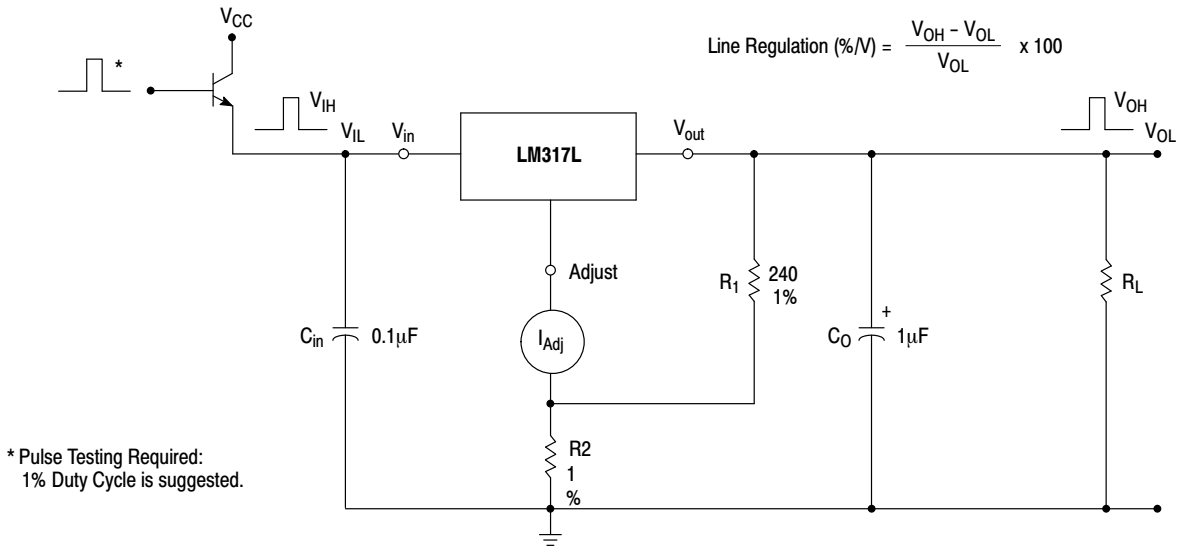


Figure 2. Line Regulation and ΔI_{Adj} /Line Test Circuit

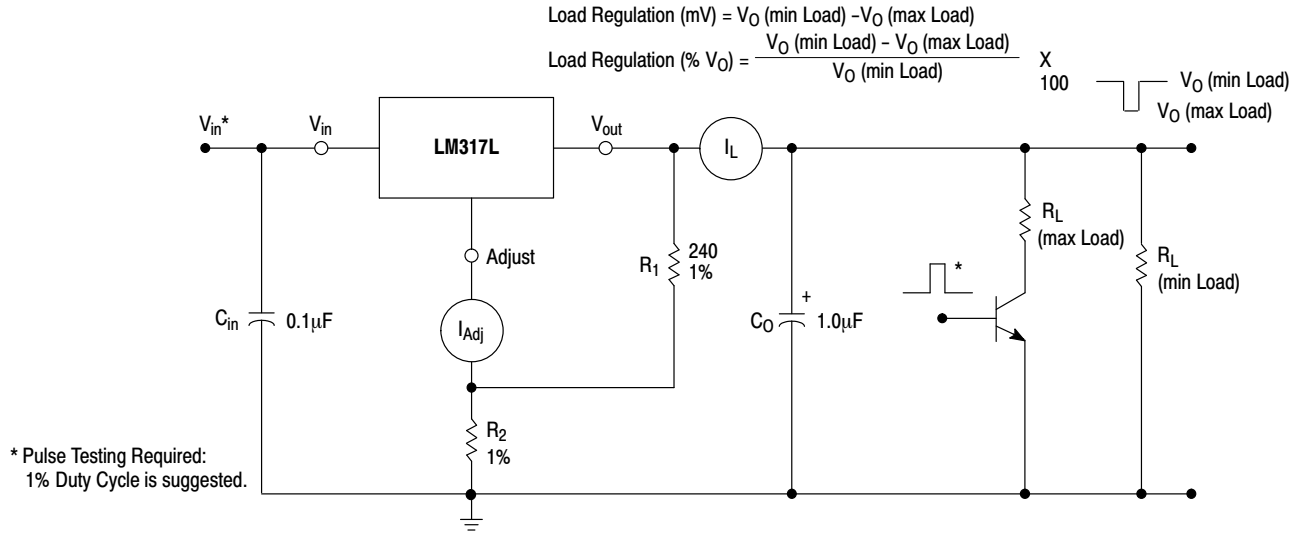


Figure 3. Load Regulation and ΔI_{Adj} /Load Test Circuit

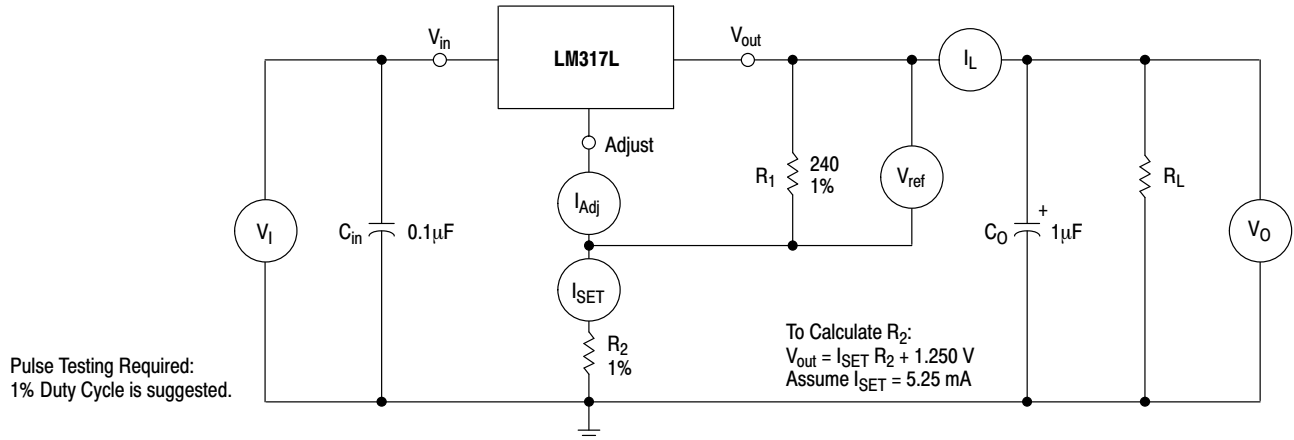
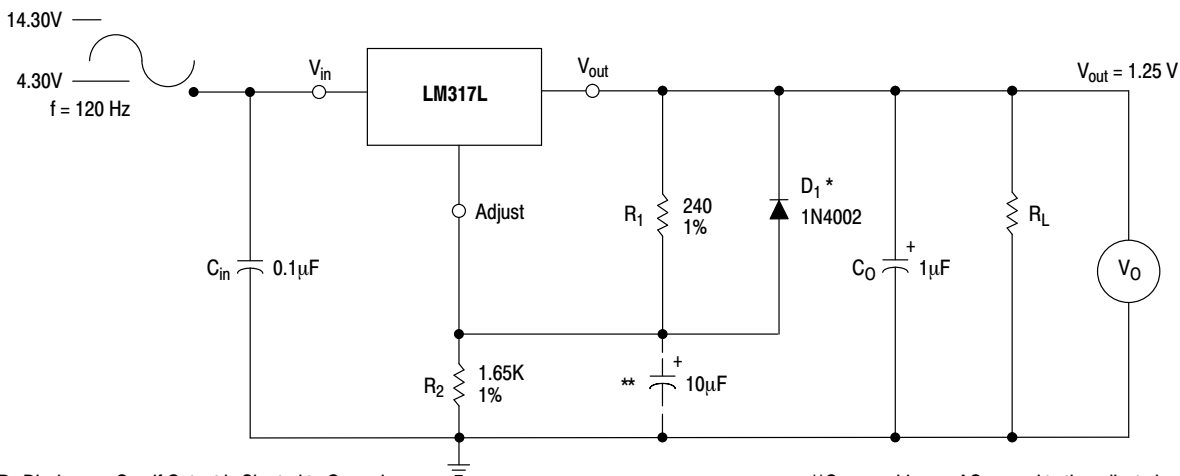


Figure 4. Standard Test Circuit

LM317L, NCV317L



* D_1 Discharges C_{Adj} if Output is Shorted to Ground.

** C_{Adj} provides an AC ground to the adjust pin.

Figure 5. Ripple Rejection Test Circuit

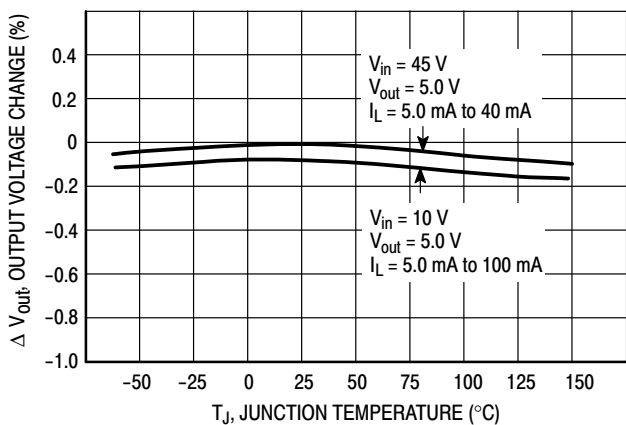


Figure 6. Load Regulation

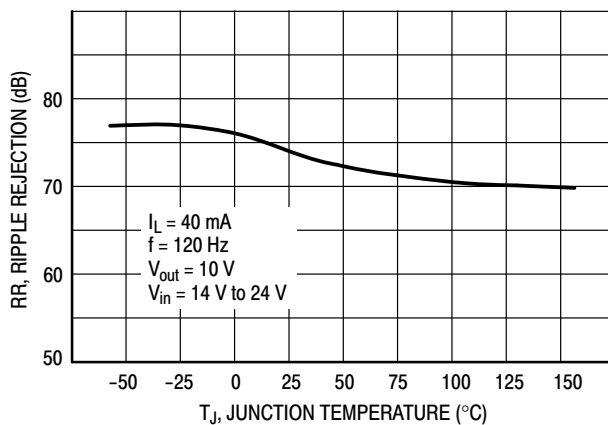


Figure 7. Ripple Rejection

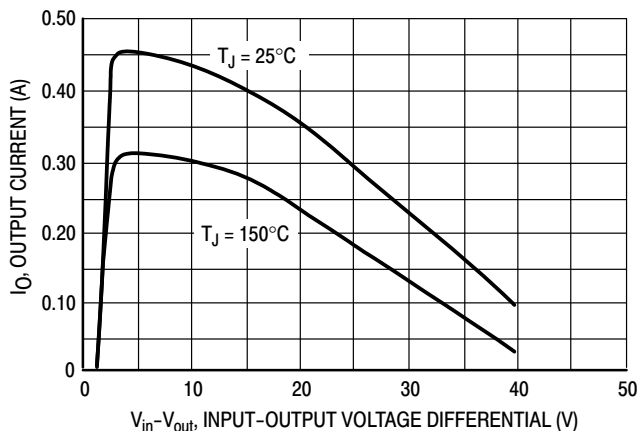


Figure 8. Current Limit

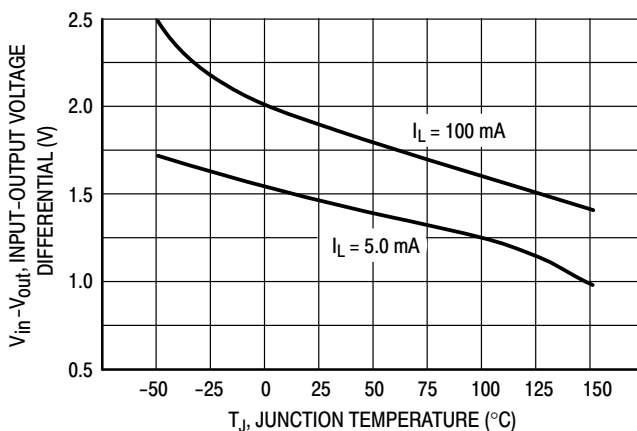


Figure 9. Dropout Voltage

LM317L, NCV317L

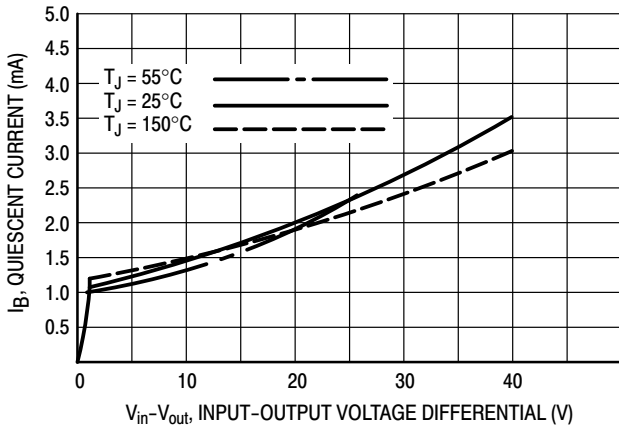


Figure 10. Minimum Operating Current

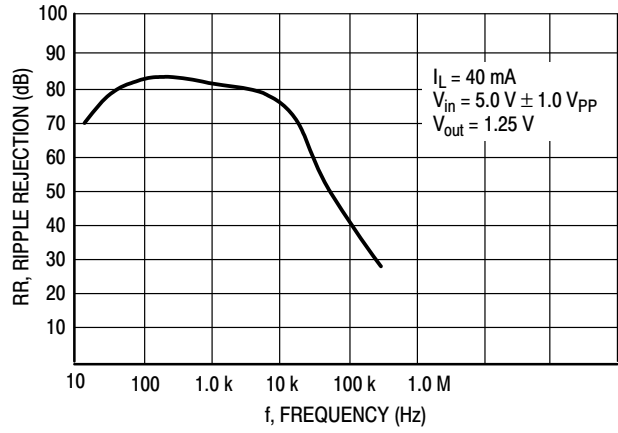


Figure 11. Ripple Rejection versus Frequency

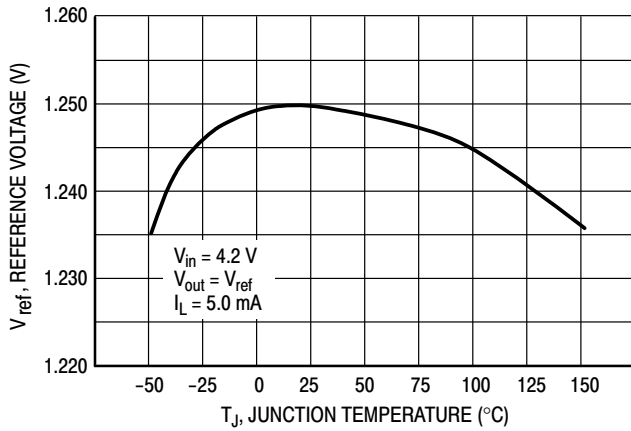


Figure 12. Temperature Stability

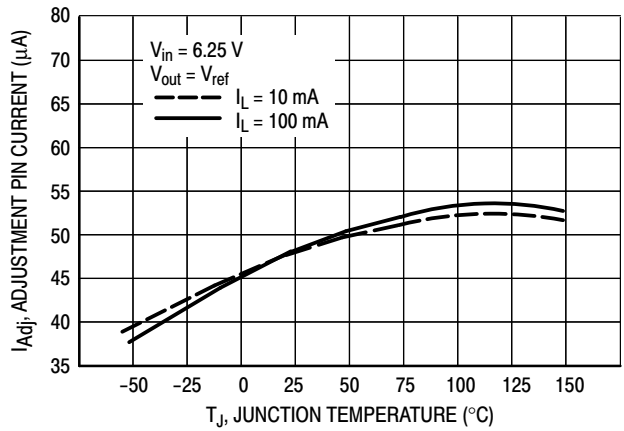


Figure 13. Adjustment Pin Current

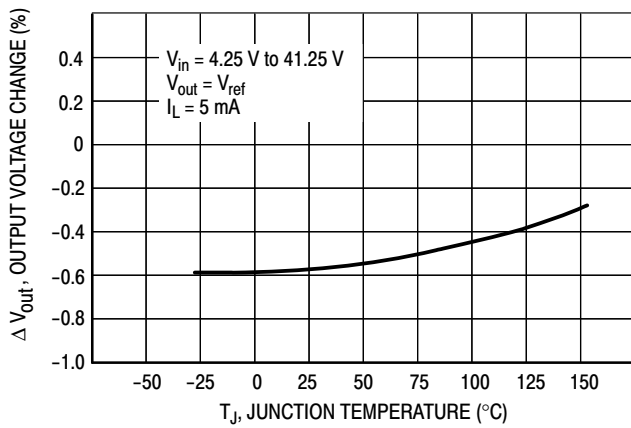


Figure 14. Line Regulation

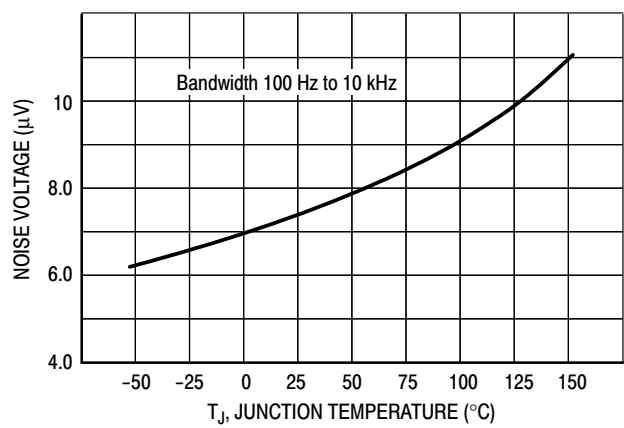


Figure 15. Output Noise

LM317L, NCV317L

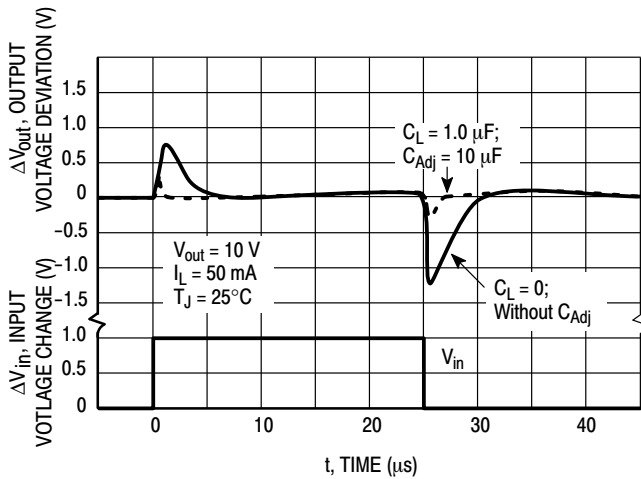


Figure 16. Line Transient Response

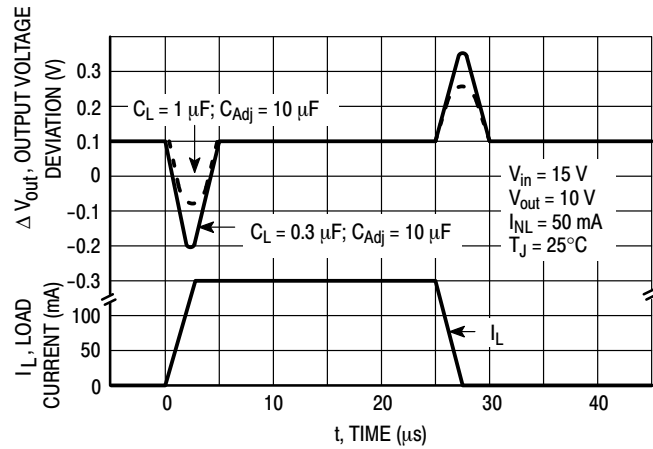


Figure 17. Load Transient Response

APPLICATIONS INFORMATION

Basic Circuit Operation

The LM317L is a 3-terminal floating regulator. In operation, the LM317L develops and maintains a nominal 1.25 V reference (V_{ref}) between its output and adjustment terminals. This reference voltage is converted to a programming current (I_{PROG}) by R_1 (see Figure 13), and this constant current flows through R_2 to ground. The regulated output voltage is given by:

$$V_{out} = V_{ref} \left(1 + \frac{R_2}{R_1} \right) + I_{Adj} R_2$$

Since the current from the adjustment terminal (I_{Adj}) represents an error term in the equation, the LM317L was designed to control I_{Adj} to less than 100 μA and keep it constant. To do this, all quiescent operating current is returned to the output terminal. This imposes the requirement for a minimum load current. If the load current is less than this minimum, the output voltage will rise.

Since the LM317L is a floating regulator, it is only the voltage differential across the circuit which is important to performance, and operation at high voltages with respect to ground is possible.

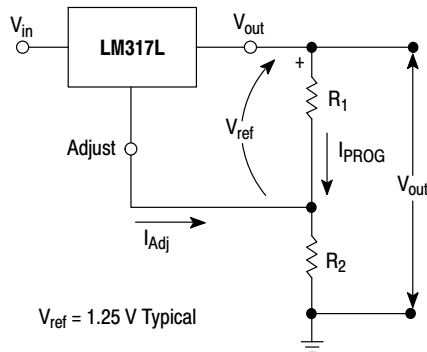


Figure 18. Basic Circuit Configuration

Load Regulation

The LM317L is capable of providing extremely good load regulation, but a few precautions are needed to obtain maximum performance. For best performance, the programming resistor (R_1) should be connected as close to the regulator as possible to minimize line drops which effectively appear in series with the reference, thereby degrading regulation. The ground end of R_2 can be returned near the load ground to provide remote ground sensing and improve load regulation.

External Capacitors

A 0.1 μF disc or 1.0 μF tantalum input bypass capacitor (C_{in}) is recommended to reduce the sensitivity to input line impedance.

The adjustment terminal may be bypassed to ground to improve ripple rejection. This capacitor (C_{Adj}) prevents ripple from being amplified as the output voltage is increased. A 10 μF capacitor should improve ripple rejection about 15 dB at 120 Hz in a 10 V application.

Although the LM317L is stable with no output capacitance, like any feedback circuit, certain values of external capacitance can cause excessive ringing. An output capacitance (C_O) in the form of a 1.0 μF tantalum or 25 μF aluminum electrolytic capacitor on the output swamps this effect and insures stability.

Protection Diodes

When external capacitors are used with any IC regulator it is sometimes necessary to add protection diodes to prevent the capacitors from discharging through low current points into the regulator.

Figure 14 shows the LM317L with the recommended protection diodes for output voltages in excess of 25 V or high capacitance values ($C_O > 10 \mu\text{F}$, $C_{Adj} > 5.0 \mu\text{F}$). Diode D_1 prevents C_O from discharging thru the IC during an input short circuit. Diode D_2 protects against capacitor C_{Adj} discharging through the IC during an output short circuit. The combination of diodes D_1 and D_2 prevents C_{Adj} from discharging through the IC during an input short circuit.

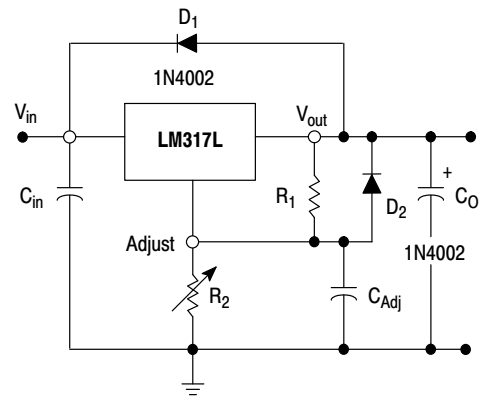


Figure 19. Voltage Regulator with Protection Diodes

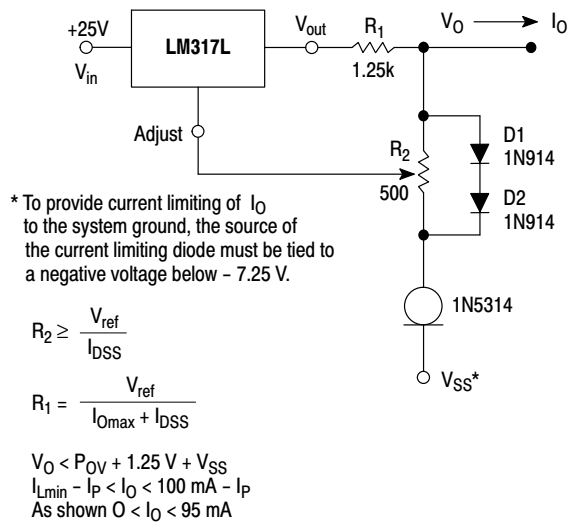
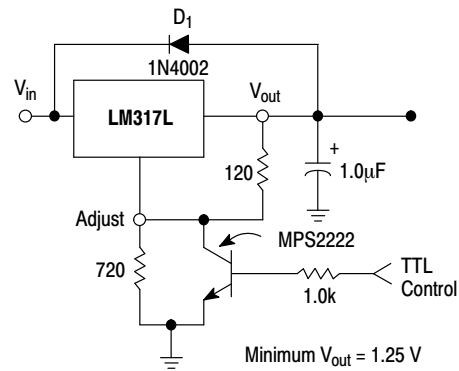


Figure 20. Adjustable Current Limiter



D_1 protects the device during an input short circuit.

Figure 21. 5.0 V Electronic Shutdown Regulator

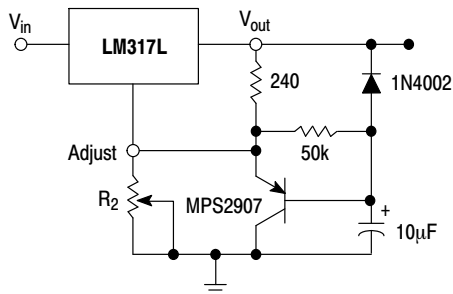
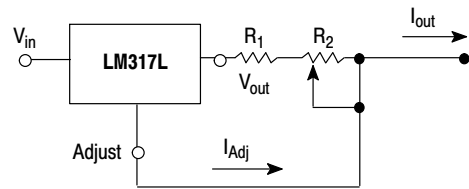


Figure 22. Slow Turn-On Regulator



$$I_{outmax} = \left(\frac{V_{ref}}{R_1} \right) + I_{Adj} \cong \frac{1.25 \text{ V}}{R_1}$$

$$I_{outmax} = \left(\frac{V_{ref}}{R_1 + R_2} \right) + I_{Adj} \cong \frac{1.25 \text{ V}}{R_1 + R_2}$$

$5.0 \text{ mA} < I_{out} < 100 \text{ mA}$

Figure 23. Current Regulator

LM317L, NCV317L

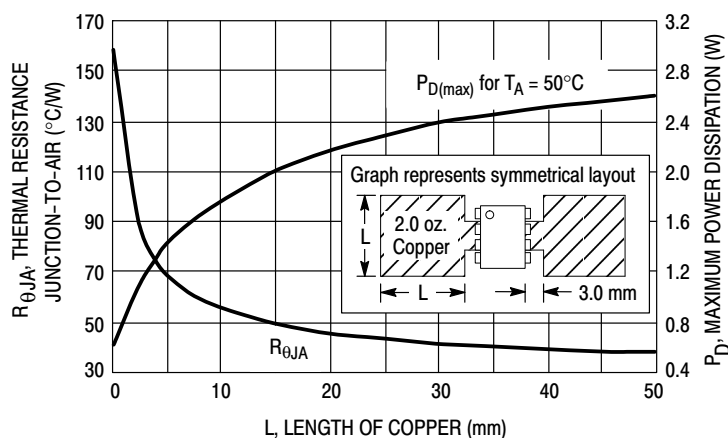
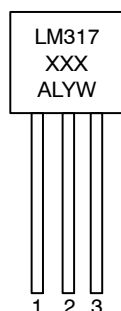


Figure 24. SOP-8 Thermal Resistance and Maximum Power Dissipation versus P.C.B. Copper Length

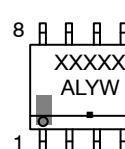
MARKING DIAGRAMS

TO-92 CASE 29-10



XXX = LBZ, LZ, LZR
 A = Assembly Location
 L = Wafer Lot
 Y = Year
 W = Work Week

SOIC-8 CASE 751



XXXXX = 317LB, LM317
 A = Assembly Location
 L = Wafer Lot
 Y = Year
 W = Work Week
 ■ = Pb-Free Package

ORDERING INFORMATION

Device	Operating Temperature Range	Package	Shipping†
LM317LBDG	$T_J = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$	SOIC-8 (Pb-Free)	98 Units / Rail
LM317LBDR2G		SOIC-8 (Pb-Free)	2500/Tape & Reel
LM317LBZG		TO-92 (Pb-Free)	2000 Units / Bag
LM317LBZRAG		TO-92 (Pb-Free)	2000 Tape & Reel
LM317LBZRPG		TO-92 (Pb-Free)	2000 Ammo Pack
NCV317LBDG*		SOIC-8 (Pb-Free)	98 Units / Rail
NCV317LBDR2G*		SOIC-8 (Pb-Free)	2500/Tape & Reel
NCV317LBZG*		TO-92 (Pb-Free)	2000 Units / Bag
NCV317LBZRAG*		TO-92 (Pb-Free)	2000 Tape & Reel
LM317LDG		$T_J = 0^{\circ}\text{C}$ to $+125^{\circ}\text{C}$	SOIC-8 (Pb-Free)
LM317LDR2G	SOIC-8 (Pb-Free)		2500/Tape & Reel
LM317LZG	TO-92 (Pb-Free)		2000 Units / Bag
LM317LZRAG	TO-92 (Pb-Free)		2000 Tape & Reel
LM317LZREG	TO-92 (Pb-Free)		2000 Tape & Reel
LM317LZRMG	TO-92 (Pb-Free)		2000 Ammo Pack
LM317LZRPG	TO-92 (Pb-Free)		2000 Ammo Pack

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NCV devices: $T_{low} = -40^{\circ}\text{C}$, $T_{high} = +125^{\circ}\text{C}$. Guaranteed by design. NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

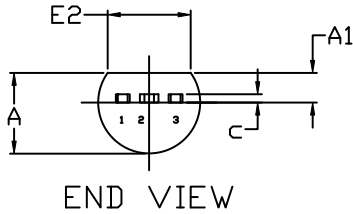
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



TO-92 (TO-226) 1 WATT
CASE 29-10
ISSUE D

DATE 05 MAR 2021

STRAIGHT LEAD



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS.
4. DIMENSION b AND b2 DOES NOT INCLUDE DAMBAR PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 0.20. DIMENSION b2 LOCATED ABOVE THE DAMBAR PORTION OF MIDDLE LEAD.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	3.75	3.90	4.05
A1	1.28	1.43	1.58
b	0.38	0.465	0.55
b2	0.62	0.70	0.78
c	0.35	0.40	0.45
D	7.85	8.00	8.15
E	4.75	4.90	5.05
E2	3.90	---	---
e	1.27 BSC		
L	13.80	14.00	14.20

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TO-92 (TO-226) 1 WATT
CASE 29-10
ISSUE D

DATE 05 MAR 2021

FORMED LEAD



END VIEW



TOP VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
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b2	0.62	0.70	0.78
c	0.35	0.40	0.45
D	7.85	8.00	8.15
E	4.75	4.90	5.05
E2	3.90	---	---
e	2.50 BSC		
L	13.80	14.00	14.20
L2	13.20	13.60	14.00
L3	3.00 REF		

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**TO-92 (TO-226) 1 WATT
CASE 29-10
ISSUE D**

DATE 05 MAR 2021

- | | | | | |
|---|--|--|---|---|
| <p>STYLE 1:
PIN 1. EMITTER
2. BASE
3. COLLECTOR</p> | <p>STYLE 2:
PIN 1. BASE
2. EMITTER
3. COLLECTOR</p> | <p>STYLE 3:
PIN 1. ANODE
2. ANODE
3. CATHODE</p> | <p>STYLE 4:
PIN 1. CATHODE
2. CATHODE
3. ANODE</p> | <p>STYLE 5:
PIN 1. DRAIN
2. SOURCE
3. GATE</p> |
| <p>STYLE 6:
PIN 1. GATE
2. SOURCE & SUBSTRATE
3. DRAIN</p> | <p>STYLE 7:
PIN 1. SOURCE
2. DRAIN
3. GATE</p> | <p>STYLE 8:
PIN 1. DRAIN
2. GATE
3. SOURCE & SUBSTRATE</p> | <p>STYLE 9:
PIN 1. BASE 1
2. EMITTER
3. BASE 2</p> | <p>STYLE 10:
PIN 1. CATHODE
2. GATE
3. ANODE</p> |
| <p>STYLE 11:
PIN 1. ANODE
2. CATHODE & ANODE
3. CATHODE</p> | <p>STYLE 12:
PIN 1. MAIN TERMINAL 1
2. GATE
3. MAIN TERMINAL 2</p> | <p>STYLE 13:
PIN 1. ANODE 1
2. GATE
3. CATHODE 2</p> | <p>STYLE 14:
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2. COLLECTOR
3. BASE</p> | <p>STYLE 15:
PIN 1. ANODE 1
2. CATHODE
3. ANODE 2</p> |
| <p>STYLE 16:
PIN 1. ANODE
2. GATE
3. CATHODE</p> | <p>STYLE 17:
PIN 1. COLLECTOR
2. BASE
3. EMITTER</p> | <p>STYLE 18:
PIN 1. ANODE
2. CATHODE
3. NOT CONNECTED</p> | <p>STYLE 19:
PIN 1. GATE
2. ANODE
3. CATHODE</p> | <p>STYLE 20:
PIN 1. NOT CONNECTED
2. CATHODE
3. ANODE</p> |
| <p>STYLE 21:
PIN 1. COLLECTOR
2. EMITTER
3. BASE</p> | <p>STYLE 22:
PIN 1. SOURCE
2. GATE
3. DRAIN</p> | <p>STYLE 23:
PIN 1. GATE
2. SOURCE
3. DRAIN</p> | <p>STYLE 24:
PIN 1. EMITTER
2. COLLECTOR/ANODE
3. CATHODE</p> | <p>STYLE 25:
PIN 1. MT 1
2. GATE
3. MT 2</p> |
| <p>STYLE 26:
PIN 1. V_{CC}
2. GROUND 2
3. OUTPUT</p> | <p>STYLE 27:
PIN 1. MT
2. SUBSTRATE
3. MT</p> | <p>STYLE 28:
PIN 1. CATHODE
2. ANODE
3. GATE</p> | <p>STYLE 29:
PIN 1. NOT CONNECTED
2. ANODE
3. CATHODE</p> | <p>STYLE 30:
PIN 1. DRAIN
2. GATE
3. SOURCE</p> |
| <p>STYLE 31:
PIN 1. GATE
2. DRAIN
3. SOURCE</p> | <p>STYLE 32:
PIN 1. BASE
2. COLLECTOR
3. EMITTER</p> | <p>STYLE 33:
PIN 1. RETURN
2. INPUT
3. OUTPUT</p> | <p>STYLE 34:
PIN 1. INPUT
2. GROUND
3. LOGIC</p> | <p>STYLE 35:
PIN 1. GATE
2. COLLECTOR
3. EMITTER</p> |

**GENERIC
MARKING DIAGRAM***



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	TO-92 (TO-226) 1 WATT	PAGE 3 OF 3

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



SCALE 1:1

SOIC-8 NB
CASE 751-07
ISSUE AK

DATE 16 FEB 2011



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*



SCALE 6:1 (mm/inches)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
■ = Pb-Free Package

XXXXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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- | | | | |
|--|---|---|---|
| <p>STYLE 1:
 PIN 1. EMITTER
 2. COLLECTOR
 3. COLLECTOR
 4. EMITTER
 5. EMITTER
 6. BASE
 7. BASE
 8. EMITTER</p> | <p>STYLE 2:
 PIN 1. COLLECTOR, DIE, #1
 2. COLLECTOR, #1
 3. COLLECTOR, #2
 4. COLLECTOR, #2
 5. BASE, #2
 6. EMITTER, #2
 7. BASE, #1
 8. EMITTER, #1</p> | <p>STYLE 3:
 PIN 1. DRAIN, DIE #1
 2. DRAIN, #1
 3. DRAIN, #2
 4. DRAIN, #2
 5. GATE, #2
 6. SOURCE, #2
 7. GATE, #1
 8. SOURCE, #1</p> | <p>STYLE 4:
 PIN 1. ANODE
 2. ANODE
 3. ANODE
 4. ANODE
 5. ANODE
 6. ANODE
 7. ANODE
 8. COMMON CATHODE</p> |
| <p>STYLE 5:
 PIN 1. DRAIN
 2. DRAIN
 3. DRAIN
 4. DRAIN
 5. GATE
 6. GATE
 7. SOURCE
 8. SOURCE</p> | <p>STYLE 6:
 PIN 1. SOURCE
 2. DRAIN
 3. DRAIN
 4. SOURCE
 5. SOURCE
 6. GATE
 7. GATE
 8. SOURCE</p> | <p>STYLE 7:
 PIN 1. INPUT
 2. EXTERNAL BYPASS
 3. THIRD STAGE SOURCE
 4. GROUND
 5. DRAIN
 6. GATE 3
 7. SECOND STAGE Vd
 8. FIRST STAGE Vd</p> | <p>STYLE 8:
 PIN 1. COLLECTOR, DIE #1
 2. BASE, #1
 3. BASE, #2
 4. COLLECTOR, #2
 5. COLLECTOR, #2
 6. EMITTER, #2
 7. EMITTER, #1
 8. COLLECTOR, #1</p> |
| <p>STYLE 9:
 PIN 1. EMITTER, COMMON
 2. COLLECTOR, DIE #1
 3. COLLECTOR, DIE #2
 4. EMITTER, COMMON
 5. EMITTER, COMMON
 6. BASE, DIE #2
 7. BASE, DIE #1
 8. EMITTER, COMMON</p> | <p>STYLE 10:
 PIN 1. GROUND
 2. BIAS 1
 3. OUTPUT
 4. GROUND
 5. GROUND
 6. BIAS 2
 7. INPUT
 8. GROUND</p> | <p>STYLE 11:
 PIN 1. SOURCE 1
 2. GATE 1
 3. SOURCE 2
 4. GATE 2
 5. DRAIN 2
 6. DRAIN 2
 7. DRAIN 1
 8. DRAIN 1</p> | <p>STYLE 12:
 PIN 1. SOURCE
 2. SOURCE
 3. SOURCE
 4. GATE
 5. DRAIN
 6. DRAIN
 7. DRAIN
 8. DRAIN</p> |
| <p>STYLE 13:
 PIN 1. N.C.
 2. SOURCE
 3. SOURCE
 4. GATE
 5. DRAIN
 6. DRAIN
 7. DRAIN
 8. DRAIN</p> | <p>STYLE 14:
 PIN 1. N-SOURCE
 2. N-GATE
 3. P-SOURCE
 4. P-GATE
 5. P-DRAIN
 6. P-DRAIN
 7. N-DRAIN
 8. N-DRAIN</p> | <p>STYLE 15:
 PIN 1. ANODE 1
 2. ANODE 1
 3. ANODE 1
 4. ANODE 1
 5. CATHODE, COMMON
 6. CATHODE, COMMON
 7. CATHODE, COMMON
 8. CATHODE, COMMON</p> | <p>STYLE 16:
 PIN 1. EMITTER, DIE #1
 2. BASE, DIE #1
 3. EMITTER, DIE #2
 4. BASE, DIE #2
 5. COLLECTOR, DIE #2
 6. COLLECTOR, DIE #2
 7. COLLECTOR, DIE #1
 8. COLLECTOR, DIE #1</p> |
| <p>STYLE 17:
 PIN 1. VCC
 2. V2OUT
 3. V1OUT
 4. TXE
 5. RXE
 6. VEE
 7. GND
 8. ACC</p> | <p>STYLE 18:
 PIN 1. ANODE
 2. ANODE
 3. SOURCE
 4. GATE
 5. DRAIN
 6. DRAIN
 7. CATHODE
 8. CATHODE</p> | <p>STYLE 19:
 PIN 1. SOURCE 1
 2. GATE 1
 3. SOURCE 2
 4. GATE 2
 5. DRAIN 2
 6. MIRROR 2
 7. DRAIN 1
 8. MIRROR 1</p> | <p>STYLE 20:
 PIN 1. SOURCE (N)
 2. GATE (N)
 3. SOURCE (P)
 4. GATE (P)
 5. DRAIN
 6. DRAIN
 7. DRAIN
 8. DRAIN</p> |
| <p>STYLE 21:
 PIN 1. CATHODE 1
 2. CATHODE 2
 3. CATHODE 3
 4. CATHODE 4
 5. CATHODE 5
 6. COMMON ANODE
 7. COMMON ANODE
 8. CATHODE 6</p> | <p>STYLE 22:
 PIN 1. I/O LINE 1
 2. COMMON CATHODE/VCC
 3. COMMON CATHODE/VCC
 4. I/O LINE 3
 5. COMMON ANODE/GND
 6. I/O LINE 4
 7. I/O LINE 5
 8. COMMON ANODE/GND</p> | <p>STYLE 23:
 PIN 1. LINE 1 IN
 2. COMMON ANODE/GND
 3. COMMON ANODE/GND
 4. LINE 2 IN
 5. LINE 2 OUT
 6. COMMON ANODE/GND
 7. COMMON ANODE/GND
 8. LINE 1 OUT</p> | <p>STYLE 24:
 PIN 1. BASE
 2. EMITTER
 3. COLLECTOR/ANODE
 4. COLLECTOR/ANODE
 5. CATHODE
 6. CATHODE
 7. COLLECTOR/ANODE
 8. COLLECTOR/ANODE</p> |
| <p>STYLE 25:
 PIN 1. VIN
 2. N/C
 3. REXT
 4. GND
 5. IOUT
 6. IOUT
 7. IOUT
 8. IOUT</p> | <p>STYLE 26:
 PIN 1. GND
 2. dv/dt
 3. ENABLE
 4. ILIMIT
 5. SOURCE
 6. SOURCE
 7. SOURCE
 8. VCC</p> | <p>STYLE 27:
 PIN 1. ILIMIT
 2. OVLO
 3. UVLO
 4. INPUT+
 5. SOURCE
 6. SOURCE
 7. SOURCE
 8. DRAIN</p> | <p>STYLE 28:
 PIN 1. SW_TO_GND
 2. DASIC OFF
 3. DASIC_SW_DET
 4. GND
 5. V_MON
 6. VBULK
 7. VBULK
 8. VIN</p> |
| <p>STYLE 29:
 PIN 1. BASE, DIE #1
 2. EMITTER, #1
 3. BASE, #2
 4. EMITTER, #2
 5. COLLECTOR, #2
 6. COLLECTOR, #2
 7. COLLECTOR, #1
 8. COLLECTOR, #1</p> | <p>STYLE 30:
 PIN 1. DRAIN 1
 2. DRAIN 1
 3. GATE 2
 4. SOURCE 2
 5. SOURCE 1/DRAIN 2
 6. SOURCE 1/DRAIN 2
 7. SOURCE 1/DRAIN 2
 8. GATE 1</p> | | |

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